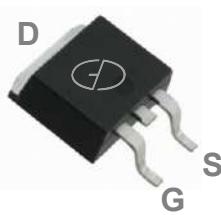
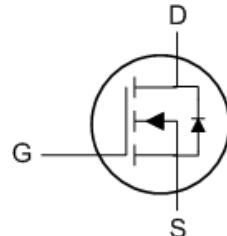


Main Product Characteristics

V_{BDSS}	800V
$R_{DS(on)}$	4.2Ω
I_D	3A



TO-252



Schematic Diagram

Features and Benefits

- Advanced MOSFET process technology
- Ideal for battery operated systems, load switching, power converters and other general purpose applications
- Low on-resistance with low gate charge
- Fast switching and reverse body recovery



Description

The SSF03N80R utilizes the latest techniques to achieve high cell density, low on-resistance and high repetitive avalanche rating. These features make this device extremely efficient and reliable for use in high efficiency switch mode power supply and a wide variety of other applications.

Absolute Maximum Ratings ($T_C=25^\circ\text{C}$ unless otherwise specified)

Parameter	Symbol	Rating	Units
Drain-Source Voltage	V_{DS}	800	V
Gate-Source Voltage	V_{GS}	± 30	V
Drain Current – Continuous ($T_c=25^\circ\text{C}$)	I_D	3	A
Drain Current – Continuous ($T_c=100^\circ\text{C}$)		1.9	A
Drain Current – Pulsed ¹	I_{DM}	12	A
Single Pulse Avalanche Energy ²	E_{AS}	283	mJ
Single Pulse Avalanche Current ²	I_{AS}	3	A
Power Dissipation ($T_c=25^\circ\text{C}$)	P_D	94	W
Power Dissipation – Derate above 25°C	P_D	0.75	W/°C
Storage Temperature Range	T_{STG}	-55 to +150	°C
Operating Junction Temperature Range	T_J	-55 to +150	°C

Thermal Characteristics

Parameter	Symbol	Typ.	Max.	Unit
Thermal Resistance Junction to Ambient	$R_{\theta JA}$	---	62	°C/W
Thermal Resistance Junction to Case	$R_{\theta JC}$	---	1.33	°C/W

Electrical Characteristics ($T_J=25^\circ\text{C}$ unless otherwise specified)

Parameter	Symbol	Conditions	Min.	Typ.	Max.	Unit
Off Characteristics						
Drain-Source Breakdown Voltage	BV_{DSS}	$\text{V}_{\text{GS}}=0\text{V}$, $\text{I}_D=250\mu\text{A}$	800	---	---	V
Drain-Source Leakage Current	I_{DSS}	$\text{V}_{\text{DS}}=800\text{V}$, $\text{V}_{\text{GS}}=0\text{V}$, $T_J=25^\circ\text{C}$	---	---	10	μA
		$\text{V}_{\text{DS}}=640\text{V}$, $\text{V}_{\text{GS}}=0\text{V}$, $T_J=100^\circ\text{C}$	---	---	100	μA
Gate-Source Leakage Current	I_{GSS}	$\text{V}_{\text{GS}}=\pm 30\text{V}$, $\text{V}_{\text{DS}}=0\text{V}$	---	---	± 100	nA
On Characteristics						
Static Drain-Source On-Resistance	$\text{R}_{\text{DS(ON)}}$	$\text{V}_{\text{GS}}=10\text{V}$, $\text{I}_D=1.5\text{A}$	---	3.36	4.2	Ω
Gate Threshold Voltage	$\text{V}_{\text{GS(th)}}$	$\text{V}_{\text{GS}}=\text{V}_{\text{DS}}$, $\text{I}_D=250\mu\text{A}$	2	---	4	V
Forward Transconductance	g_{fs}	$\text{V}_{\text{DS}}=30\text{V}$, $\text{I}_D=1.5\text{A}$	---	3.7	---	S
Dynamic and Switching Characteristics						
Total Gate Charge ^{3,4}	Q_g	$\text{V}_{\text{DS}}=640\text{V}$, $\text{V}_{\text{GS}}=10\text{V}$, $\text{I}_D=3\text{A}$	---	19	---	nC
Gate-Source Charge ^{3,4}	Q_{gs}		---	4	---	
Gate-Drain Charge ^{3,4}	Q_{gd}		---	7.6	---	
Turn-On Delay Time ^{3,4}	$\text{T}_{\text{d(on)}}$	$\text{V}_{\text{DD}}=400\text{V}$, $\text{V}_{\text{GS}}=10\text{V}$, $\text{R}_g=25\text{W}$ $\text{I}_D=3\text{A}$	---	48	---	ns
Rise Time ^{3,4}	T_r		---	36	---	
Turn-Off Delay Time ^{3,4}	$\text{T}_{\text{d(off)}}$		---	106	---	
Fall Time ^{3,4}	T_f		---	41	---	
Input Capacitance	C_{iss}	$\text{V}_{\text{DS}}=25\text{V}$, $\text{V}_{\text{GS}}=0\text{V}$, $\text{F}=1\text{MHz}$	---	696	---	pF
Output Capacitance	C_{oss}		---	65	---	
Reverse Transfer Capacitance	C_{rss}		---	10.2	---	
Drain-Source Diode Characteristics and Maximum Ratings						
Continuous Source Current	I_s	$\text{V}_{\text{G}}=\text{V}_{\text{D}}=0\text{V}$, Force Current	---	---	3	A
Pulsed Source Current	I_{SM}		---	---	6	A
Diode Forward Voltage	V_{SD}	$\text{V}_{\text{GS}}=0\text{V}$, $\text{I}_s=1\text{A}$, $T_J=25^\circ\text{C}$	---	---	1.5	V
Reverse Recovery Time ³	t_{rr}	$\text{V}_{\text{GS}}=0\text{V}$, $\text{I}_s=3\text{A}$, $\text{dI}/\text{dt}=100\text{A}/\mu\text{s}$	---	372	---	nS
Reverse Recovery Charge ³	Q_{rr}	$T_J=25^\circ\text{C}$	---	1.8	---	μC

Notes :

- Repetitive Rating : Pulsed width limited by maximum junction temperature.
- $\text{V}_{\text{DD}}=50\text{V}$, $\text{V}_{\text{GS}}=10\text{V}$, $\text{I}_s=59\text{mH}$, $\text{I}_{\text{AS}}=3\text{A}$, $\text{R}_g=25\Omega$, Starting $T_J=25^\circ\text{C}$.
- The data tested by pulsed, pulse width $\leq 300\mu\text{s}$, duty cycle $\leq 2\%$.
- Essentially independent of operating temperature.

Typical Electrical and Thermal Characteristics

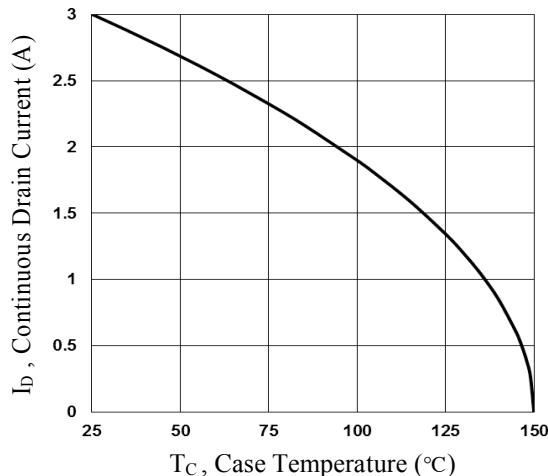


Fig.1 Continuous Drain Current vs. T_C

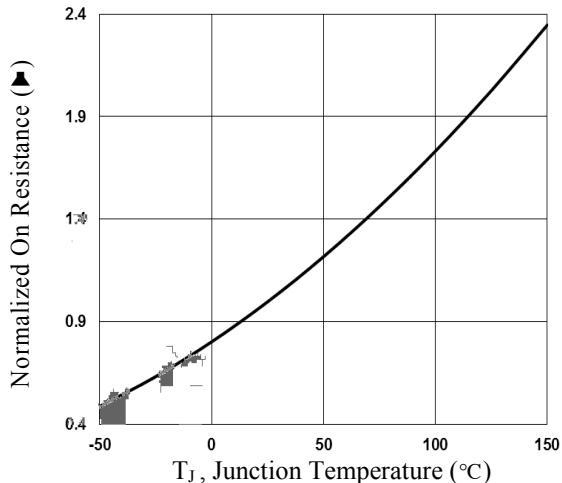


Fig.2 Normalized RD_{SON} vs. T_J

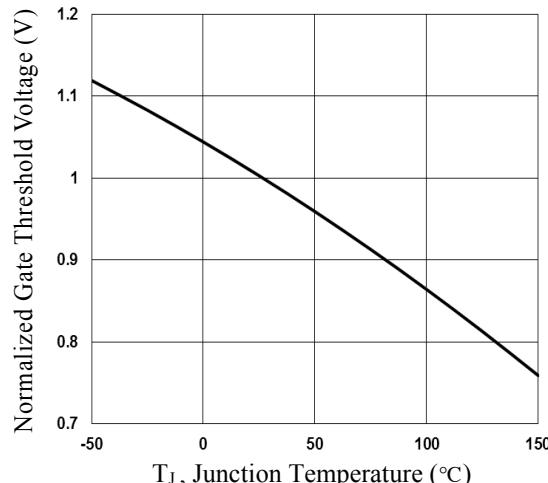


Fig.3 Normalized V_{th} vs. T_J

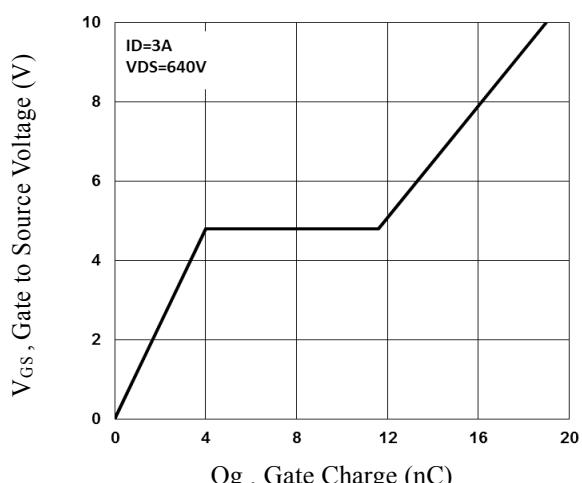


Fig.4 Gate Charge Waveform

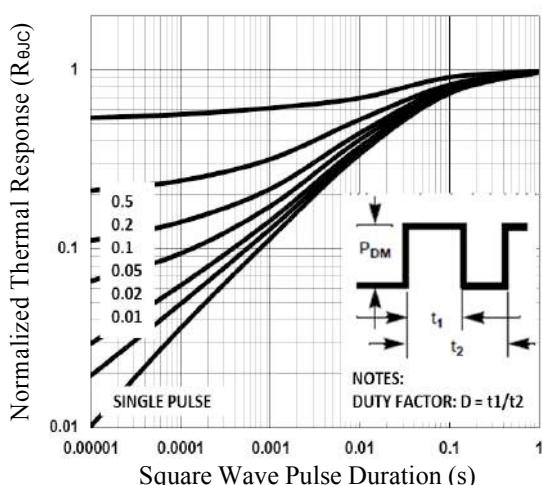


Fig.5 Normalized Transient Impedance

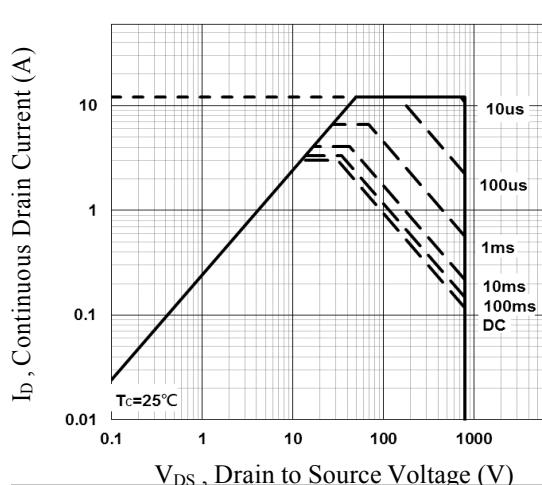


Fig.6 Maximum Safe Operation Area

Typical Electrical and Thermal Characteristics

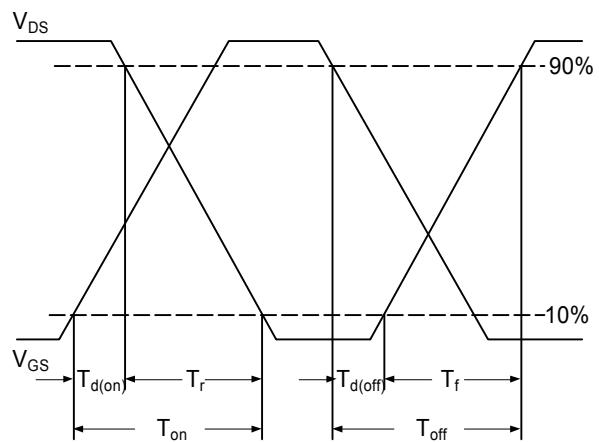


Fig.7 Switching Time Waveform

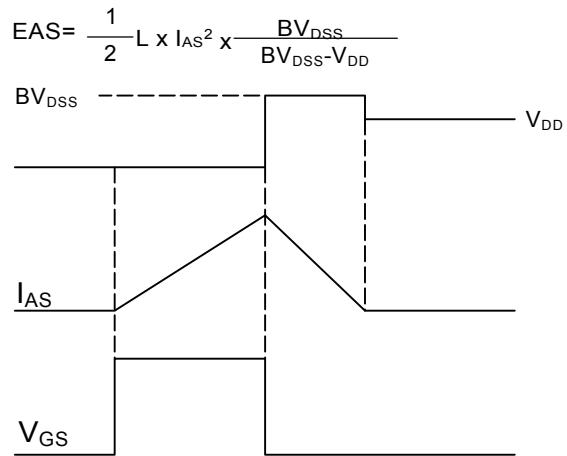
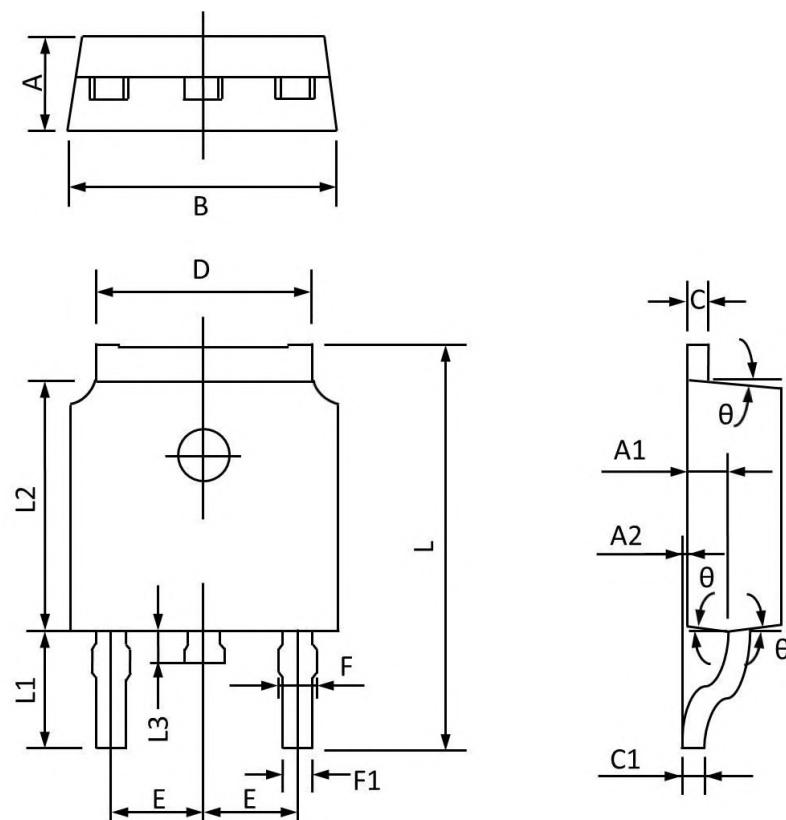


Fig.8 EAS Waveform

Package Outline Dimensions

TO-252



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min	Max	Min	Max
A	2.20	2.40	0.087	0.094
A1	0.91	1.11	0.036	0.044
A2	0.00	0.15	0.000	0.006
B	6.50	6.70	0.256	0.264
C	0.46	0.580	0.018	0.230
C1	0.46	0.580	0.018	0.030
D	5.10	5.46	0.201	0.215
E	2.186	2.386	0.086	0.094
F	0.74	0.94	0.029	0.037
F1	0.660	0.860	0.026	0.034
L	9.80	10.40	0.386	0.409
L1	2.9REF		0.114REF	
L2	6.00	6.20	0.236	0.244
L3	0.60	1.00	0.024	0.039
θ	3°	9°	3°	9°